

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

Product Summary



V_{DS}	-60	V
I_D	-25	A
$R_{DS(ON)}$ (at $V_{GS}=-10V$)	40	m Ω

Applications

- High Frequency Point-of-Load, Synchronous Buck Converter
- Networking DC-DC Power System
- Load Switch



Absolute Maximum Ratings($T_C=25^{\circ}C$, unless otherwise noted)

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V_{DS}	-60	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ¹	I_D	-25	A
Continuous Drain Current ¹	I_D	-17.7	A
Pulsed Drain Current ²	I_{DM}	-60	A
Single Pulse Avalanche Energy ³	EAS	300	mJ
Total Power Dissipation ⁴	P_D	90	W
Storage Temperature Range	T_{STG}	-55 to 150	$^{\circ}C$
Operating Junction Temperature Range	T_J	-55 to 150	$^{\circ}C$

Thermal Characteristics

Parameter	Symbol	Typ	Max	Unit
Thermal Resistance Junction-Case ¹	$R_{\theta JC}$	---	1.4	$^{\circ}C/W$

Electrical Characteristics (T_J=25°C, unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =-250uA	-60	---	---	V
Static Drain-Source On-Resistance	R _{DS(ON)}	V _{GS} =-10V, I _D =-20A	---	33	40	mΩ
Gate Threshold Voltage	V _{GS(th)}	V _{GS} =V _{DS} , I _D =-250uA	-1	-1.5	-2.5	V
Drain-Source Leakage Current	I _{DSS}	V _{DS} =-48V, V _{GS} =0V, T _J =25°C	---	---	-1	uA
Gate-Source Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	---	---	±100	nA
Forward Transconductance	g _{fs}	V _{DS} =-10V, I _D =-10A	---	25	---	S
Total Gate Charge	Q _g	V _{DS} =-30V, V _{GS} =-10V, I _D =-10A	---	46	---	nC
Gate-Source Charge	Q _{gs}		---	9.5	---	
Gate-Drain Charge	Q _{gd}		---	10.5	---	
Turn-On Delay Time	T _{d(on)}	V _{DD} =-30V, V _{GS} =-10V, R _G =3Ω, R _L =1.5Ω	---	12	---	ns
Rise Time	T _r		---	15	---	
Turn-Off Delay Time	T _{d(off)}		---	38	---	
Fall Time	T _f		---	15	---	
Input Capacitance	C _{iss}	V _{DS} =-30V, V _{GS} =0V, f=1MHz	---	3130	---	pF
Output Capacitance	C _{oss}		---	321	---	
Reverse Transfer Capacitance	C _{rss}		---	212	---	

Drain-Source Diode Characteristics

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Continuous Source Current ¹	I _S	T _C =25°C	---	---	-25	A
Diode Forward Voltage ²	V _{SD}	V _{GS} =0V, I _S =-10A, T _J =25°C	---	---	-1.1	V
Reverse Recovery Time	t _{rr}	I _F =-10A, di/dt=100A/μs, T _J =25°C	---	47	---	nS
Reverse Recovery Charge	Q _{rr}		---	53	---	nC

Note:

- The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%
- The EAS data shows Max. rating. The test condition is V_{DD}=-20V, V_{GS}=-10V, L=1mH
- The power dissipation is limited by 150°C junction temperature

Typical Characteristics

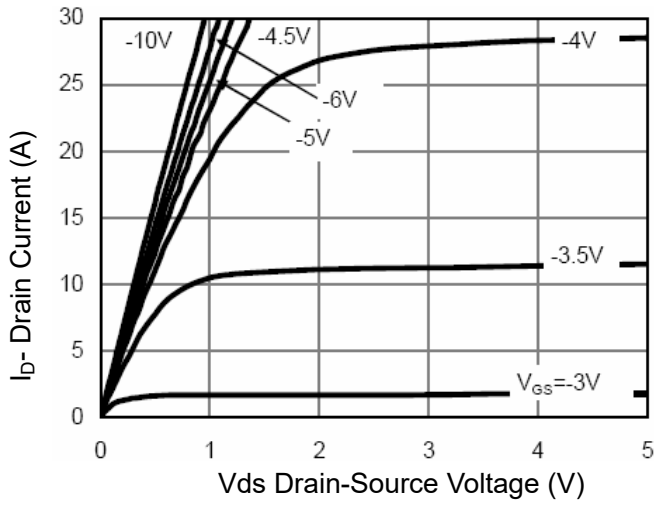


Figure 1 Output Characteristics

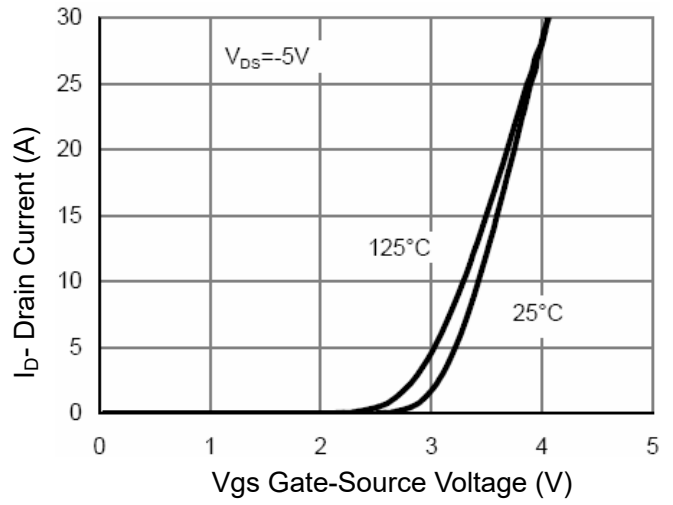


Figure 2 Transfer Characteristics

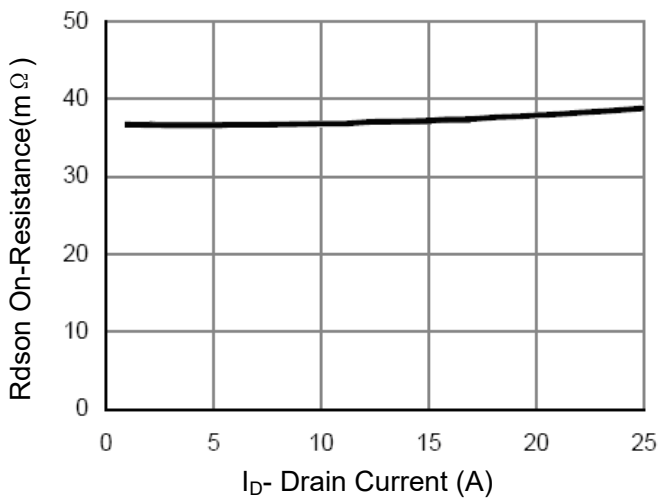


Figure 3 Rdson- Drain Current

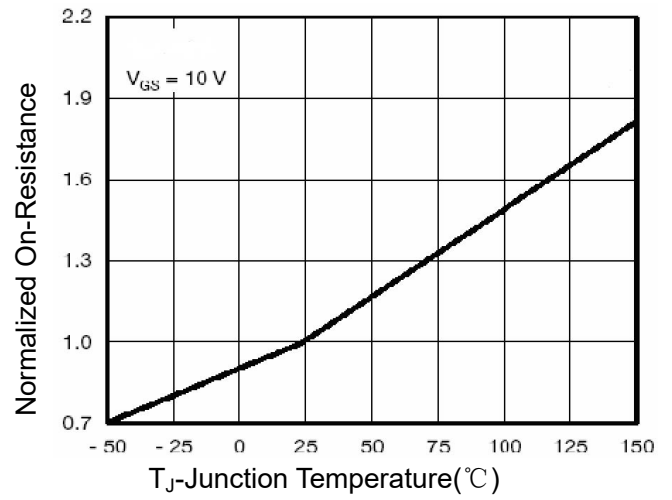


Figure 4 Rdson-Junction Temperature

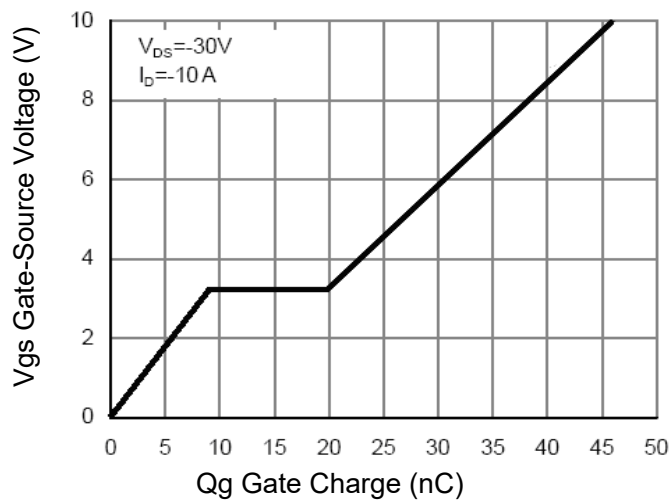


Figure 5 Gate Charge

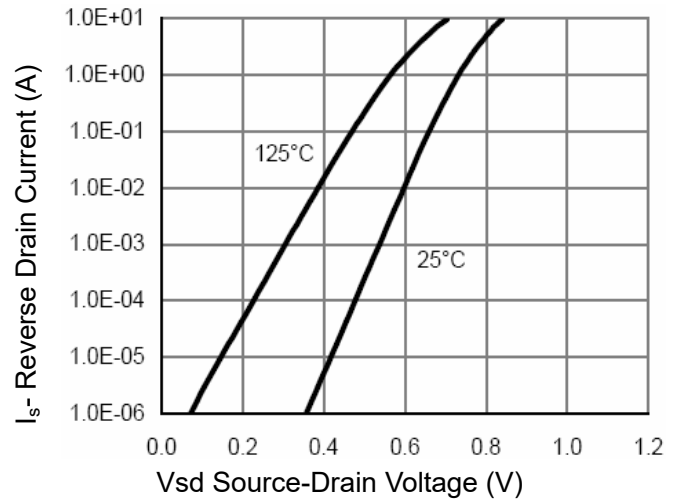


Figure 6 Source- Drain Diode Forward

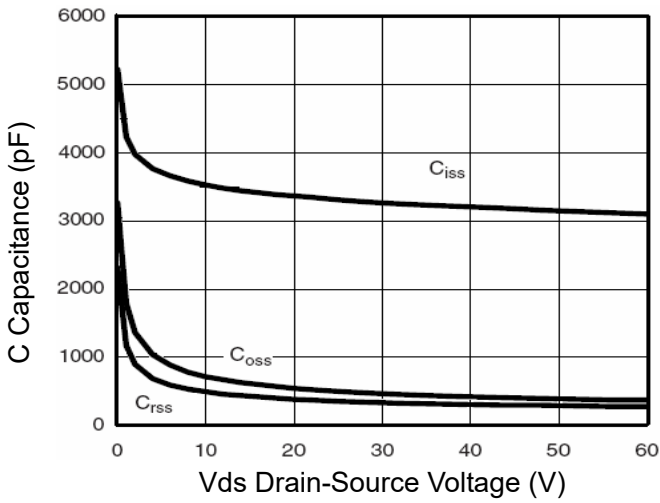


Figure 7 Capacitance vs Vds

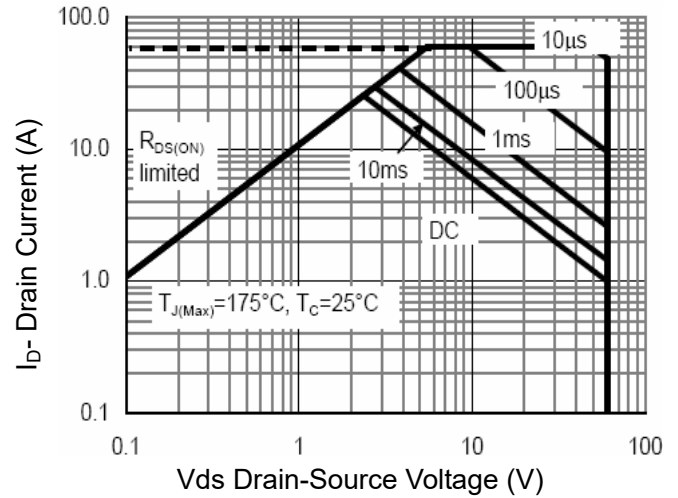


Figure 8 Safe Operation Area

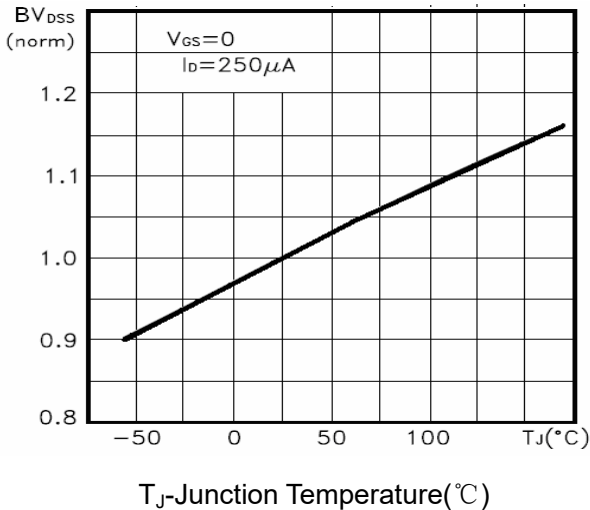


Figure 9 BV_{DSS} vs Junction Temperature

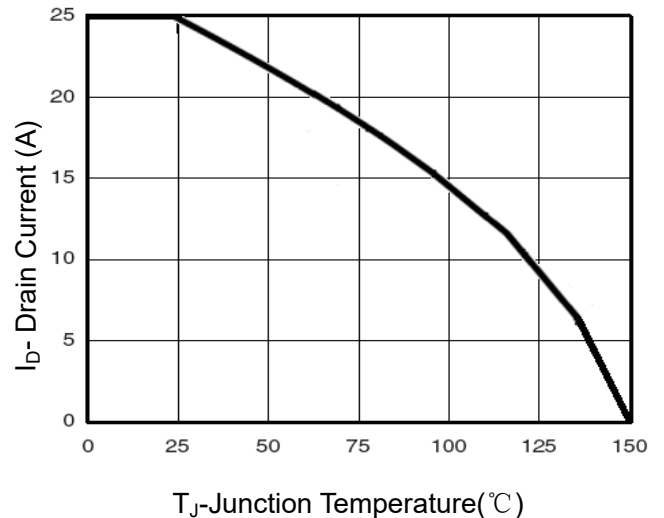


Figure 10 ID Current De-rating

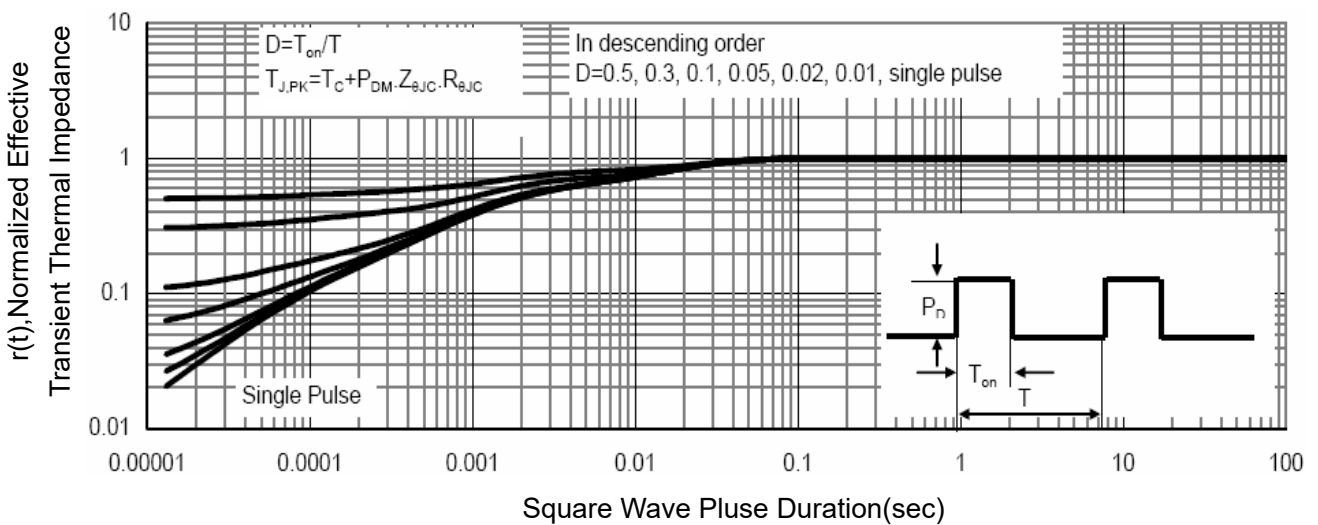
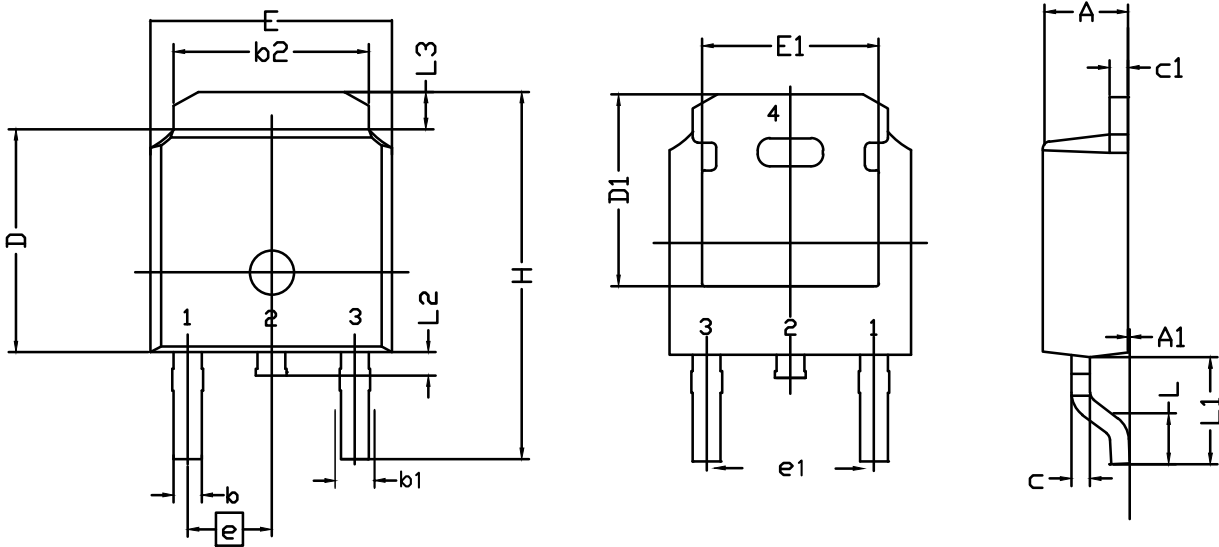


Figure 11 Normalized Maximum Transient Thermal Impedance

TO-252 Package Outline Dimensions



Symbol	Dimensions (unit:mm)			Symbol	Dimensions (unit:mm)		
	Min	Typ	Max		Min	Typ	Max
A	2.20	2.30	2.38	E	6.40	6.60	6.731
A₁	0.00	0.10	0.20	E₁	4.40	--	--
b	0.64	0.76	0.89	e	2.286 BSC		
b₁	0.77	0.85	1.14	e₁	4.572 BSC		
b₂	5.00	5.33	5.46	H	9.40	10.00	10.40
c	0.458	0.508	0.610	L	1.40	1.52	1.77
C₁	0.458	0.508	0.620	L₁	--	2.743	--
D	5.98	6.10	6.223	L₂	0.60	0.80	1.01
D₁	5.20	5.25	5.38	L₃	0.90	1.06	1.25